

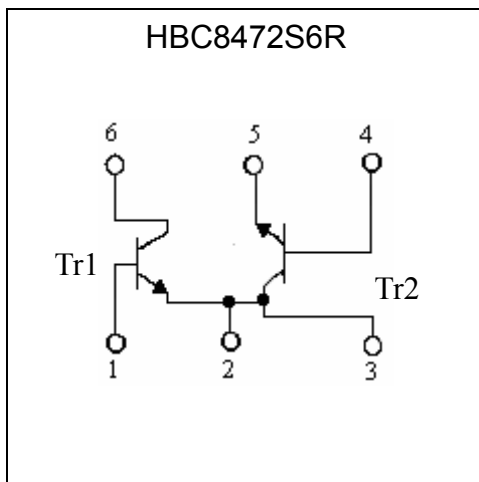
General Purpose NPN Epitaxial Planar Transistors (dual transistors)

HBC8472S6R

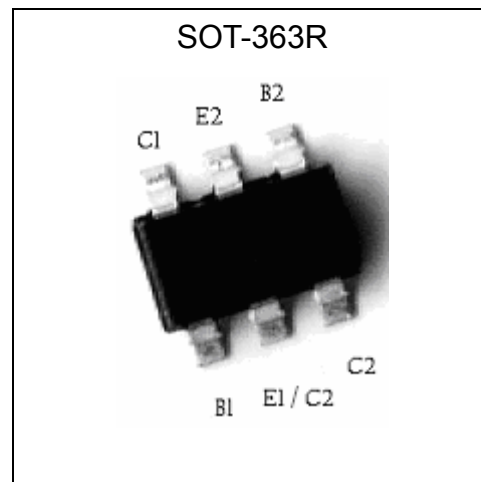
Features

- Two BTC2412 chips in a SOT-363R package.
- Mounting possible with SOT-323 automatic mounting machines.
- Transistor elements are independent, eliminating interference.
- Mounting cost and area can be cut in half.
- Low Cob. Typ. Cob=2.0pF
- Pb-free package

Equivalent Circuit



Outline



The following characteristics apply to both Tr1 and Tr2

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V _{CBO}	60	V
Collector-Emitter Voltage	V _{CEO}	50	V
Emitter-Base Voltage	V _{EBO}	6	V
Collector Current	I _C	200	mA
Power Dissipation	P _D	200(total) (Note)	mW
Junction Temperature	T _j	150	°C
Storage Temperature	T _{stg}	-55~+150	°C

Note : 150mW per element must not be exceeded.



Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV _{CBO}	60	-	-	V	I _C =100μA
BV _{CEO}	50	-	-	V	I _C =1mA
BV _{EBO}	6	-	-	V	I _E =50μA
I _{CBO}	-	-	100	nA	V _{CB} =60V
I _{EBO}	-	-	100	nA	V _{EB} =5V
V _{CE(sat)}	-	-	0.3	V	I _C =100mA, I _B =10mA
V _{BE(sat)}	-	-	1	V	I _C =100mA, I _B =10mA
h _{FE}	200	-	560	-	V _{CE} =6V, I _C =1mA
h _{FE}	25	-	-	-	V _{CE} =6V, I _C =150mA
f _T	80	160	-	MHz	V _{CE} =12V, I _C =2mA, f=100MHz
C _{ob}	-	2	4	pF	V _{CB} =10V, f=1MHz

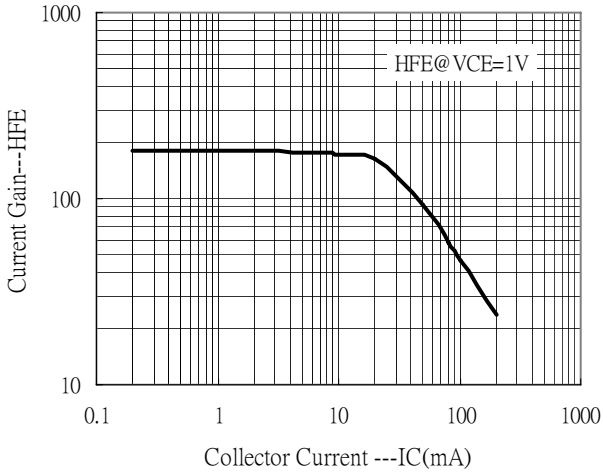
*Pulse Test: Pulse Width ≤380μs, Duty Cycle ≤2%

Ordering Information

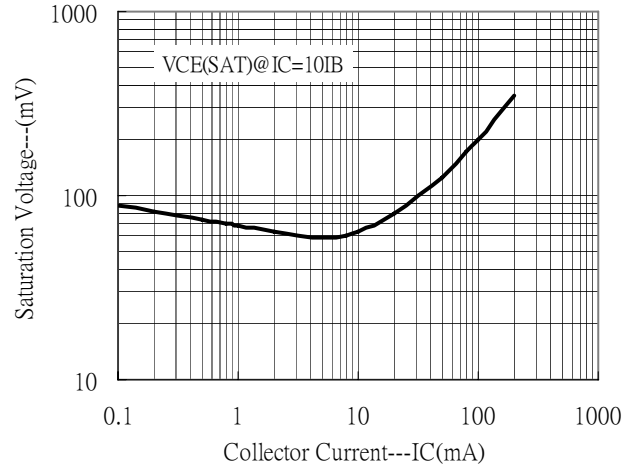
Device	Package	Shipping	Marking
HBC8472S6R	SOT-363 (Pb-free)	3000 pcs / Tape & Reel	CK

Characteristic Curves

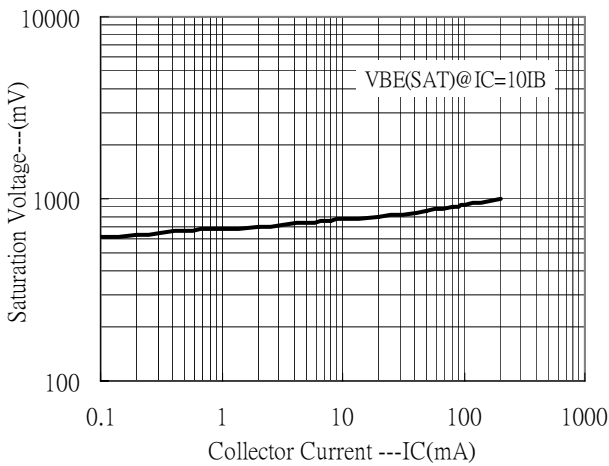
Current Gain vs Collector Current



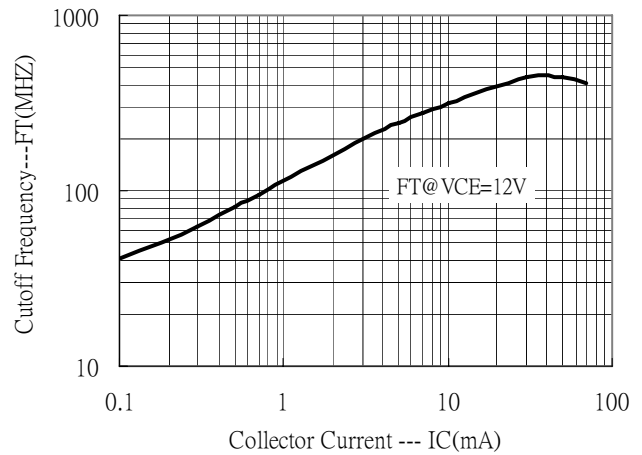
Saturation Voltage vs Collector Current



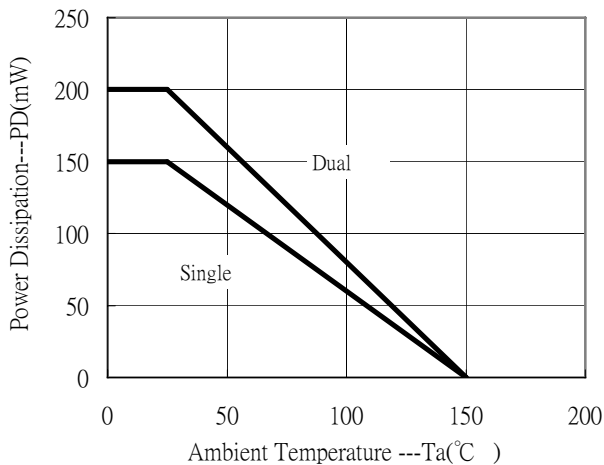
Saturation Voltage vs Collector Current



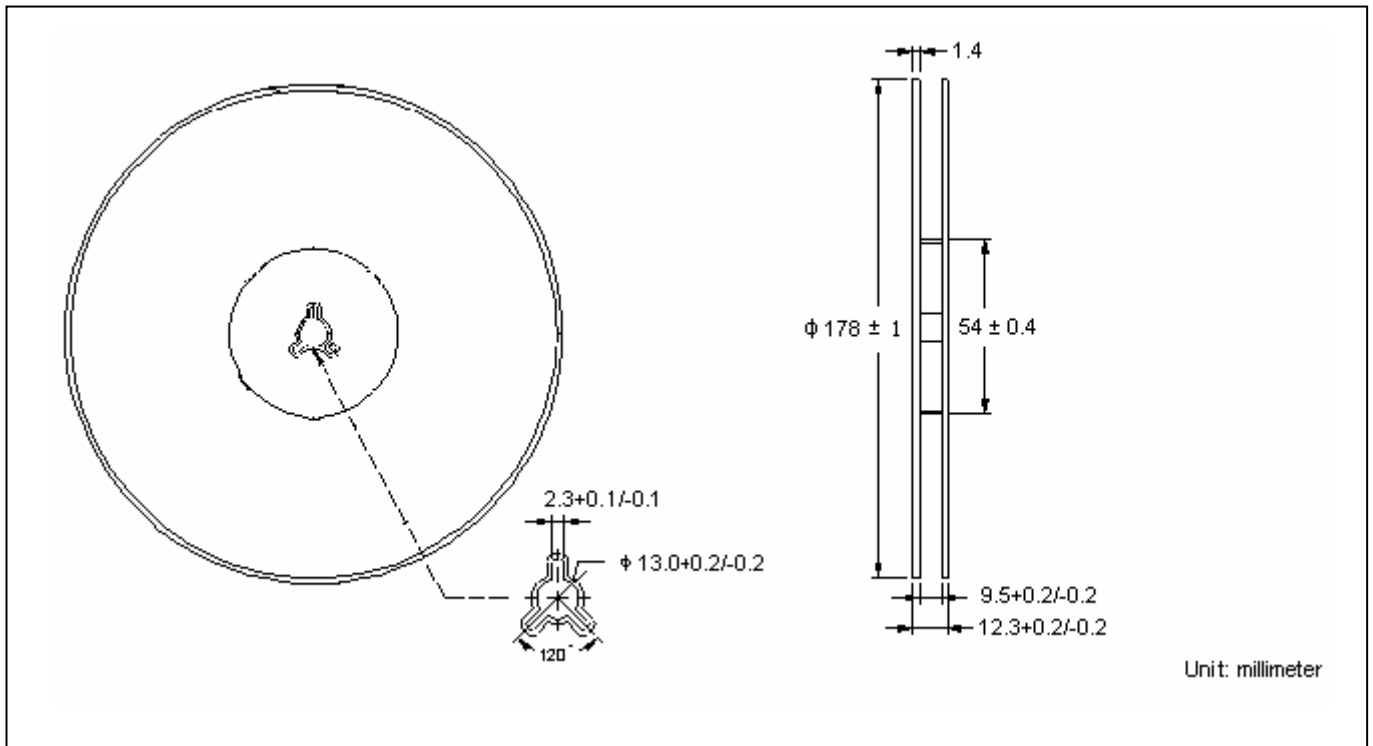
Cutoff Frequency vs Collector Current



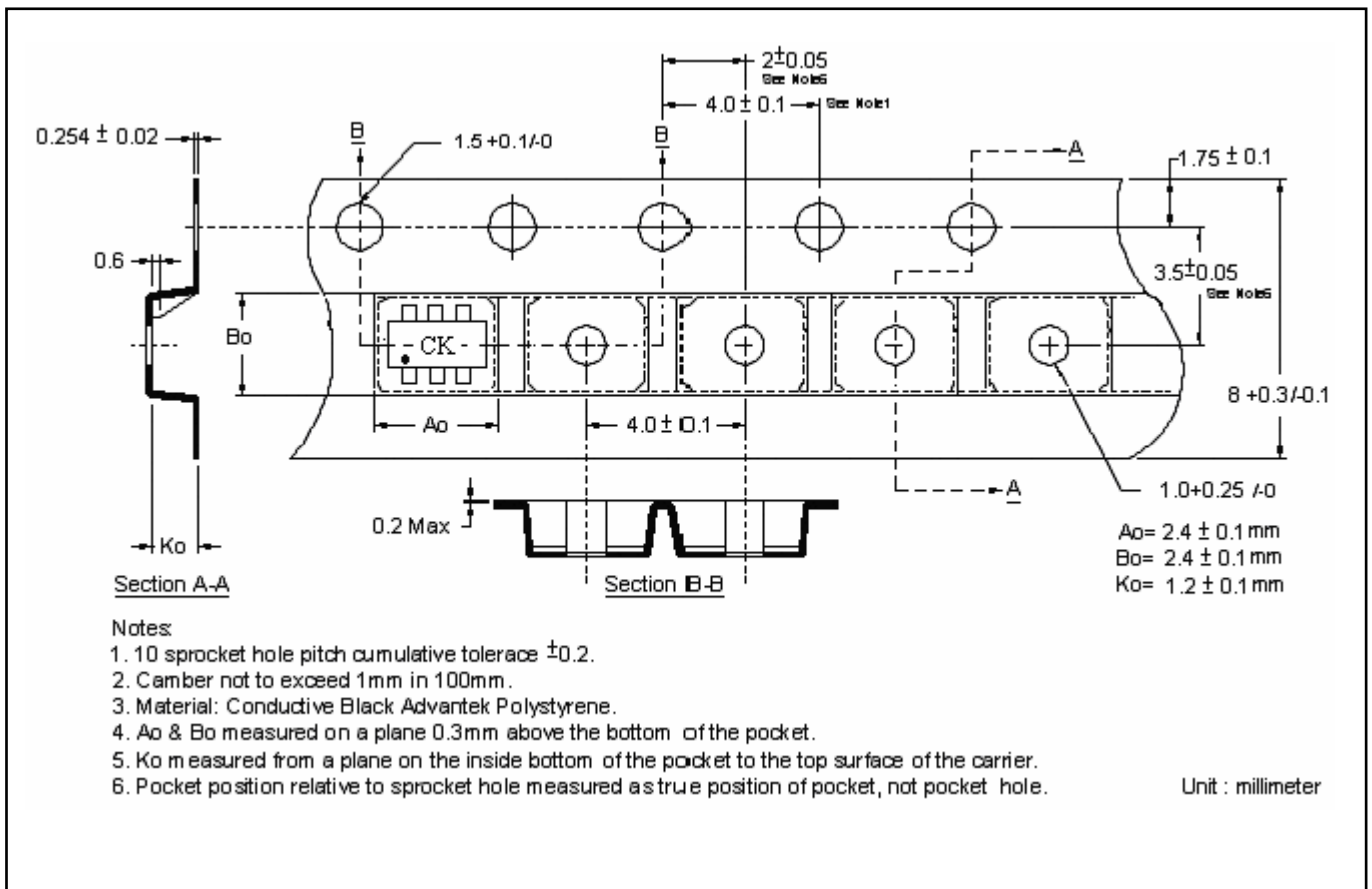
Power Derating Curves



Reel Dimension



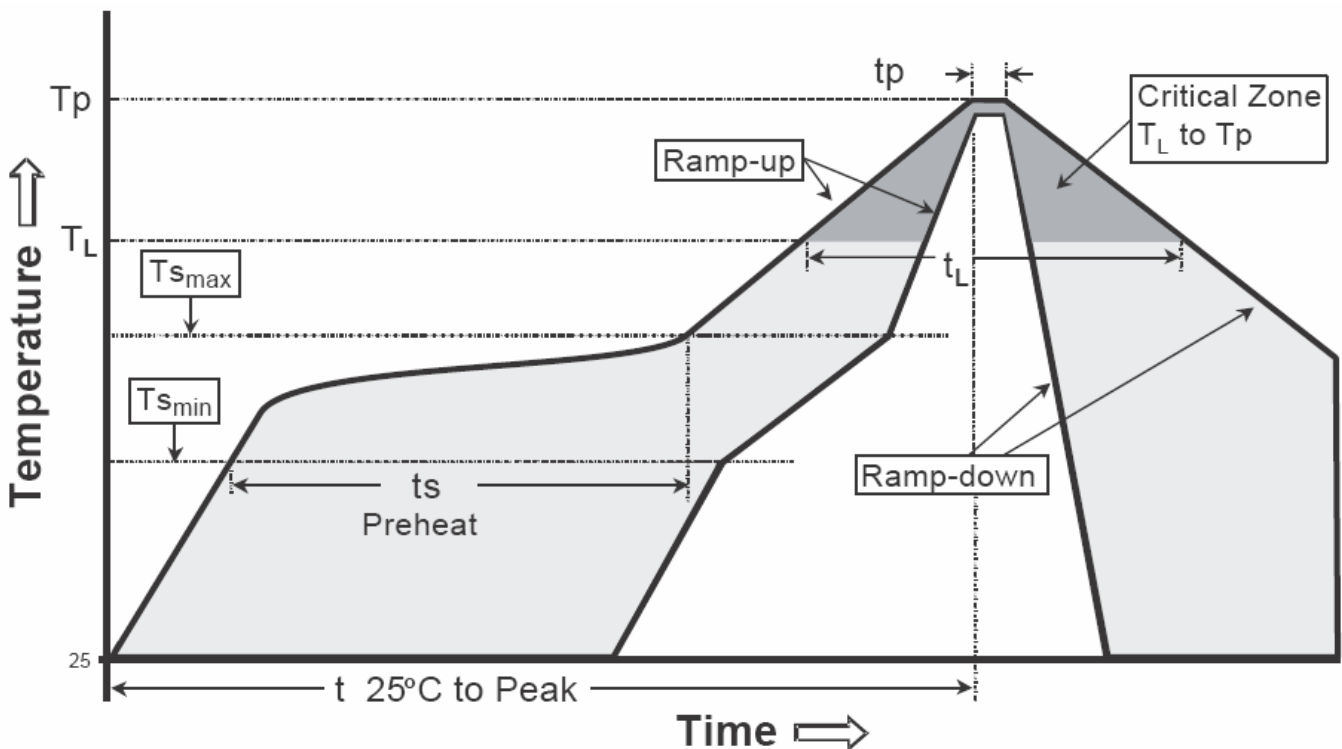
Carrier Tape Dimension



Recommended wave soldering condition

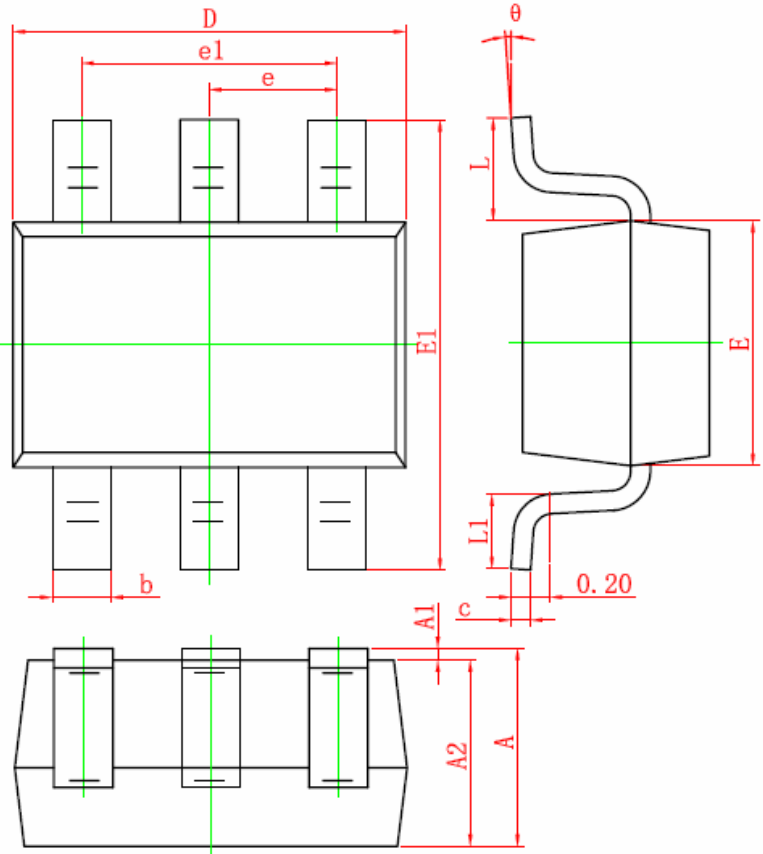
Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow



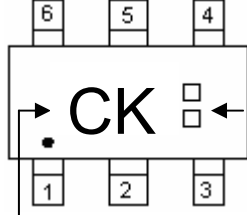
Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T _{smax} to T _p)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(T _{s min})	100°C	150°C
-Temperature Max(T _{s max})	150°C	200°C
-Time(t _{s min} to t _{s max})	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (T _L)	183°C	217°C
- Time (t _L)	60-150 seconds	60-150 seconds
Peak Temperature(T _P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

SOT-363 Dimension



The diagram shows three views of the SOT-363R package: a top view, a side view, and a bottom view. Dimensions are labeled with letters and numbers. The top view shows dimensions D, e1, e, and b. The side view shows dimensions E1, E, L, L1, c, and 0.20. The bottom view shows dimensions A1, A2, and A. An angle θ is also indicated.

Marking:



Date Code:
 Year + Month
 Year : 6→2006,
 7→2007,..., etc
 Month : 1→Jan
 2→Feb, ..., 9→
 Sep, A→Oct, B
 →Nov, C→Dec

Device Code

6-Lead SOT-363R Plastic
 Surface Mounted Package
 CYStek Package Code: S6R

Style:
 Pin 1. Base1 (B1)
 Pin 2. Emitter1/Collector2 (E1/C2)
 Pin 3. Collector2 (C2)
 Pin 4. Base2 (B2)
 Pin 5. Emitter2 (E2)
 Pin 6. Collector1 (C1)

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.900	1.100	0.035	0.043	E1	2.150	2.450	0.085	0.096
A1	0.000	0.100	0.000	0.004	e	0.650	TYP	0.026	TYP
A2	0.900	1.000	0.035	0.039	e1	1.200	1.400	0.047	0.055
b	0.150	0.350	0.006	0.014	L	0.525	REF	0.021	REF
c	0.080	0.150	0.003	0.006	L1	0.260	0.460	0.010	0.018
D	2.000	2.200	0.079	0.087	θ	0°	8°	0°	8°
E	1.150	1.350	0.045	0.053					

Notes : 1.Controlling dimension : millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material :

- Lead : Pure tin plated.
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0.

Important Notice:

- All rights are reserved. Reproduction in whole or in part is prohibited without the prior written approval of CYStek.
- CYStek reserves the right to make changes to its products without notice.
- CYStek **semiconductor products are not warranted to be suitable for use in Life-Support Applications, or systems.**
- CYStek assumes no liability for any consequence of customer product design, infringement of patents, or application assistance.